

OATH AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below-named inventor, being duly sworn, I hereby depose and say that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled "INTEGRATED CIRCUIT CHIP PACKAGE", the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby depose and say that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true.

I hereby appoint: William R. Clark, Registration No. 29,523
Donald F. Mofford, Registration No. 33,740
Glenn H. Lenzen, Jr., Registration No. 29,320

my attorneys or agents, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, with the said William R. Clark having full power of revocation of any power given to any other attorney or agent in this application, and request that all correspondence be directed to:

William R. Clark
Raytheon Company
Patent Department
141 Spring Street
Lexington, MA 02173

Raytheon Case No. 36694
APP-4
10/21/94

[illegible]

SEAL